

PCN# : P1AEA Issue Date : Oct. 26, 2011

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Oct. 31, 2011

Expected First Date Code of Changed Product :1145

Last Date for Shipment of Unchanged Product : Oct. 31, 2011

Description of Change (From) :

Sumitomo Thailand leadframe supplier.

Description of Change (To) : Qualify ASM Singapore as an

alternate leadframe supplier.

				Sumitomo (Current)		ASM (2 nd Source)		
Frame stock#	FSID	Package Type	Base Metal	Roughen Process	Таре	Base Metal	Roughen Process	Tape
500749	FSA9280AUMX, FSA9280AUMX_F 065, FSA9280AUMX_S N00227, FSA9280UMX FSA9288AUMX	UMLP 20L 3X4mm	Cu (C194)	No Roughening Process Used NiPd Au Plating	Nitto	Cu (C194)	No Roughening Process Used NiPd Au Plating	Nitto
500798	FDMS7603S FDMS7621S FDMS7600AS FDMS7602S FDMS7606 FDMS7608S FDMS7620S FDMS7700S	MLP 8L 5X6mm	Cu (C194)	Yes-Cu Roughen	Hitachi	Cu (C194)	No Roughening Process Used NiPd Au Plating	Hitachi
500726	FAN5353MPX, FAN5354MPX, FAN5902MPX,	MLP 12L 3.5X3mm	Cu (C194)	No Roughening Process Used NiPd Au Plating	Hitachi	Cu (C194)	No Roughening Process Used NiPd Au Plating	Hitachi
500681	FDMA6023PZT, SN00198 FDFMA2P853T FDFMA2P859T FDMA1027PT FDMA6023PZT	MLP 6L 2x2mm	Cu (C194)	No Roughening Process Used NiPd Au Plating	Hitachi	Cu (C194)	No Roughening Process Used NiPd Au Plating	Hitachi
500462	FDMS2572 FDMS2672 FDMS2734 FDMS3572 FDMS3672 FDMS5672	MLP 8L 5x6mm	Cu (C194)	No Roughening Process Used NiPd Au Plating	Nitto	Cu (C194)	No Roughening Process Used NiPd Au Plating	Nitto
500905	FDMA710PZ FDMA0104 FDMA507PZ	MLP 6L 2.05x2.05 mm	Cu (C194)	Yes-Cu Roughen	Hitachi	Cu (C194)	No Roughening Process Used NiPd Au Plating	Hitachi

Reason for Change:

Recent flooding at our primary leadframe supplier, Sumitomo in Thailand, has caused that factory to stop shipments for the foreseeable future until the floodwaters recede, damage assessed and repair and requalification activities completed. This change is being pursued to mitigate supply risk to our customer base. Fairchild has previously qualified ASM as a leadframe supplier for other MLP products.

The change will not impact product form, fit or function. The internal qualification data is available for review upon customer request.

Affected Product(s):

FAN5353MPX	FAN5354MPX	FAN5902MPX
FDFMA2P853T	FDFMA2P859T	FDMA0104
FDMA1027PT	FDMA507PZ	FDMA6023PZT
FDMA6023PZT_SN00198	FDMA710PZ	FDMS2572
FDMS2672	FDMS2734	FDMS3572
FDMS3672	FDMS5672	FDMS7600AS
FDMS7602S	FDMS7603S	FDMS7606
FDMS7608S	FDMS7620S	FDMS7621S
FDMS7700S	FSA9280AUMX	FSA9280AUMX_F065
FSA9280AUMX_SN00227	FSA9280UMX	FSA9288AUMX

Qualification Plan	Device	Package	Process	No. of Lots
Q20060353	FAN5068MPX	MLP 24 5X5	CS80CBI	3

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/495
Autoclave	121C, 100%RH	JESD22-A102	96 hrs	0/231
Bond Pull		JESD22-C100		0/75
Steam Aging	(8 hr), Condition A Solder Dip(215C, 5 sec) (Solderability)	JESD22-B102	8 hrs	0/66
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/231